





Status of gaseous DHCAL R&D in Europe

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1



R&D with small gaseous prototypes

> Toward ILC DHCAL prototyping

DHCAL motivation

- Particle Flow Approach requires high longitudinal and transverse granularity in calorimetry for precise jet measurement
- It implies highly segmented steel sandwich hadron calorimeter (HCAL)
- Digital Hadron Calorimeter (DHCAL) may provide fine segmentation (~1cm²) with simplest yes/no read out system which is enough for neutral hadron pattern recognition and muon ID



Gaseous active medium candidates



MicroMegas gain ~10^5, high rate



LAPP (Annecy) + collaborators R&D is started

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DHCAL RPC performance

RPC pad size



DHCAL RPC performance

It was choosen in beam tests in IHEP with small 4x4 pads RPCs

LES I Hamburg

5 GeV/c h⁺ beam

<u>RPC samples</u>
▶ 1.2, 1.6, 2.0 gaps
▶ 10¹³ Ω·cm window glass
▶ 4x4 pads of 1x1 cm²

In saturated avalanche and streamer modes with TFE based mixtures: avalanche: TFE/IB/SF6=(90-93)/5/(5-3) % streamer : TFE/IB/Ar or N2=80/10/10 %

Trigger S1·S2·S3·S4 for 2x2 cm² area

FE(D_i) – 16 ch. preamp+disc based on discrete elements, on side

Avalanche mode was selected





RPC in avalanche mode

Typical Q and m distributions 1.2 mm, 2% SF₆, 8.4 kV - working point, 2.2 mV thr



RPC in streamer mode

Typical Q and M distributions, 200 V above knee 1.2 mm gap, TFE/Ar/IB=80/10/10



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Comparison of avalanche and streamer modes

Rate capability streamer ~2-3 Hz/cm² avalanche ~100 Hz/cm²

It is hard to work in streamer mode even for usual beam conditions

Streamer is suitable only for very low rates like e+e⁻ ILC



Comparison

of avalanche and streamer modes

As example, for 1.2 mm gap

| N⁰ | Item | avalanche | streamer |
|----|-------------------------------------|--------------------|---------------------|
| 1 | Working mixture | TFE/Iso/SF6=93/5/2 | TFE/Iso/Ar=80/10/10 |
| 2 | HV working point, kV | 7.4 | 7.4 |
| 3 | Induced charge, pC | 3.4 | 400 |
| 4 | Threshold on 50Ω , mV | 1-2 | 300 |
| 5 | Efficiency, % | ~98 | ~95 |
| 6 | σ_0 / Q | ~ 0.9 | ~ 0.6 |
| 7 | Pad multiplicity | 1.4-1.5 | 1.2 - 1.3 |
| 8 | Noise, Hz/cm ² | ~ 0.7 | ~ 0.1 |
| 9 | Rate capability, Hz/cm ² | 100 | 2 - 3 |
| | | | |

DHCAL RPC features

Geant3 simulations



Summary of RPC features

| N⁰ | Item | Value | Comments |
|----|-------------------------------------|------------------------------------|------------------|
| 1 | Pad size | <u>1x1 cm2</u> | |
| 2 | Number of gaps | monogap | |
| 3 | Mode of operation | saturated avalanche | |
| 4 | Working mixture | TFE/Iso/SF6=93/5/2 | |
| 5 | Gas gap | 1.2 mm | 1.6 mm can be |
| 6 | Resistive plates | thin glass,10 [^] 13 Ω·cm | used |
| 7 | HV working point, kV | 7.4 | |
| 8 | Induced charge, pC | ~3 | |
| 9 | Threshold on 50 Ω , mV | 1-2 | |
| 10 | Efficiency, % | ~98 | |
| 11 | HV plateau | ~600 V | |
| 12 | σο / Q | ~ 1 | |
| 13 | Pad multiplicity | 1.4-1.5 ? | |
| 14 | Noise, Hz/cm ² | ~ 0.5 | |
| 15 | Rate capability, Hz/cm ² | ≤100 | |
| 16 | Resistivity of HV coverage | $> 10^{6} \Omega/ sq$ | |
| 17 | Control of RPC work | Q RO of cathode strips | |
| 18 | Maximal own RPC thickness | <u>6 mm</u> | try to keep 5 mm |
| | with 2 mm SS cups | <u>10 + 0.5 mm</u> | 14 mm AHCAL |

Combined RPC

Our results confirm first observation of ANL group about combined RPC – low hit multiplicity, <m> ~ 1.1 at 95% with 400 V plateau.

It seems that the combined RPC is promising option for the DHCAL. Long term stability study of combined RPC is underway.





RPC performance selection and design

1.2 mm monogap glass RPC, saturate avalanche mode 98% eff , 1 kV plateau, ~1.4 mult Combined RPC – mult < 1.1

| Ν | Item | Thick, mm | |
|---|---------------------|-----------|---|
| 1 | Anode printed board | 1.0 | |
| 2 | Insulated mylar | 0.05 | |
| 3 | Graphite coverage | 0.05 | |
| 4 | Glass anode | 0.55 | |
| 5 | Gas gap | 1.2 | |
| 6 | Glass cathode | 0.85 | |
| 7 | Graphite coverage | 0.1 | |
| 8 | Insulated mylar | 0.2 | |
| 9 | Cathode PB | 0.5 | |
| | Thickness budget | 4.5 | |
| | Max thickness | <8.0 | 1 |
| | Room for FEE | ~ 3.5 | |



Anode PCB – internal surface for pads, external one for RO electronics Cathode PCB – internal surface for long strips for QDC read out (control)

Tests of 64 channels RPCs in 5T mag field

RPCs with 8x8 pads of 1x1 cm2 area were tested with new specially designed 64 channel FEE



PCB is on side of RPC and includes 8 channel MINSK chips OKA (amp.+disc.), ALTERA EP1K50 as FPGA and RS232 driver for sequental read out with PC <u>FPGA</u> -Signals written on coincidence with trigger 64 bits for signals + 10 bits for trigger N -Info is storaged in FIFO -Read out by PC with end of spill signal



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Tests of 64 channels RPCs in 5T mag field

There is no evidence of the 5Tmagnetic field influence on the RPC performance



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7.8

HV(kV)

Tests of 32x32 pads RPC

RPC with sensitive area of 36x96 cm2 was produce to incorporate 32x32 =1024 pads of 1 cm2 area.

For read-out the 2 anode PBs with 16x32=512 pads were used. Connections between pads and the 64 ch. FEE are made by microcoax 50 ohm cables. Cosmic ray tests were done due to lack of beam time.

It was concluded that on side FEE is dead end for 1 m2 plane. Special on board ASIC with serial output is needed.





DHCAL µMEGAS Study

R&D is ongoing for µMEGAS chambers with 8X8 pads, 6X16 pads, 50X50 pads of 1cm2 (collaboration with Saclay) to select the performance for DHCAL



6X16 pad µMEGAS chamber(LAPP,IPNL)

1m³ DHCAL prototype

It is intended to construct ~1m3 DHCAL prototype with solutions near ILC detector requirements:

- Single active layer plane (no dead zones)
- ASIC with power pulsing
- On board front end
- CALICE DAQ2 system
- Integrated gas, HV, LV systems

Furthermore it is needed to validate gaseous approaches, to compare with MC simulations and Sc. HCAL

If 1x1 cm2 cells and 40 layers with 20 mm steel plates as absorber then ~400,000 channels are needed Existing mechanical structure can be used

Key question is FE ASIC

Two steps in realization:

- Slab construction and tests
- Full ~1m3 construction and tests

Comparison of hadron shower simulation codes by G Mavromanolakis





ASIC – HARDROC1

Was produced and tested successfully

LAL, IPNL, LLR

- Full power pulsing
- Digital memory: Data saved during bunch train.
- Only one serial output
- Store all channels and BCID for every hit. Depth = 128 bits
- Data format : 128(depth)*[2bit*64ch+ 24bit(BCID)+8bit(Heade r)] = 20kbits
- Sequential readout @ 1 MHz

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NSM

Test board with packaged HaRDROC chip



Chip performance are found as expected. Low channel-to-channel X-talk (<2%)

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HARDROC1 PERFORMANCE SUMMARY

| Number of inputs/outputs | 64 inputs, 1 serial output |
|---------------------------------|---|
| | |
| Input Impedance | 50-70Ω |
| Gain Adjustment | 0 to 4, 6bits, accuracy 6% |
| Bipolar Fast Shaper | ≈3.5 mV/fC tp=15ns |
| 10 bit-DAC | 2.5 mV/fC, INL=0.2% |
| Trigger sensitivity | Down to 10fC |
| | |
| Slow Shaper (analog readout) | \approx 50 mV/pC, 5fC to 15pC , tp= 50ns to 150ns |
| Analog Xtk | 2% |
| Analog Readout speed | 5 MHz |
| | |
| Memory depth | 128 (20kbits) |
| Digital readout speed | 5MHz or more |
| | |
| Power dissipation (not pulsed) | 100 mW (64 channels) |





8x32 pads RPC

4 RPCs with 8x32 read out pads were produced. One chamber was sent to Lyon.Chambers are waiting for anode PCBs with HADROCK chips



8x32 pads PCB

800 µ thick 8-layers PCB with blind and buried vias
8X32 pads, 1 cm2 surface with 500µ separation between pads
6 PCBs were produced





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DHCAL Acquisition with HaRDROC VFE – Kobe may '07

Time schedule 2007 for Slab study

| • | Assembly (soldering) of 3 PCBs | June 10 |
|--|---|-----------------|
| • | Check of soldering PCBs | June 15 |
| • | Development of the DAQ | June 15 |
| • | Full assembly of one 8x32 RPC | end of June |
| • | Tests with cosmics | July CRITICAL |
| • | Tests in e beam at DESY | September |
| • | Tests of µMEGAS Slab in cosmics Comparison of RPC and µMEGAS perform | October ance |
| N.B : The PCB was conceived to be compatible with | | |

μMEGAS detector as well.

~1m3 DHCAL prototype

If Slab tests are OK and funding is available then roughly:

| • | Construction, cosmics tests of 1st 1m2 RPC plane with strips in IHEP | , |
|---|--|-------|
| | sending to Lyon. The same for µMEGAS in Annecy. | Dec0' |

- **Construction of cosmics stand for tomography of pad 1m2 RPC** Dec07 ۲ planes in Lyon
- **Comparison between RPC/µMEGAS performance in Lyon** Jan08 with cosmics stand to select the proper active media for the DHCAL prototype. Final Hardrock, PCB, DAQ
- **Build elements of DHCAL prototype** Dec08 ٠ Jun09 ۲
- Assembly and beam tests of the DHCAL prototype

IPNL(Lyon) starts to be DHCAL center





RPC



μMEGAS

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1m² RPC plane

As prototype for 1 m3 DHCAL prototype



1000x1030 mm2 - lateral dimensions 970 x 970 mm2 – glass area 960 x 960 mm2 – sensitive area Weight ~ 40 kg



96x96 = 9216 anode pads in total 24 anode PCBs of 80x530 mm2 8x48 = 384 pads on each = 6 Hardrock ASIC

SS cups and Al bar frame form hermetic box. It prevents glass break due to gas overpressure.

1m² RPC plane with strip read out

Construction of 1 m2 RPC plane





Gas volume: anode glass -0.5 mm thick, cathode glass -0.8 mm thick, 1.2 mm gas gap, 6 mm dia spacers

96x6 cm2 strips for read-out 16 anode (x) strips 16 cathode (y) strips

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Tests of 1m² RPC plane with strip read-out

Detailed study of the plane was performed in cosmic rays.

In general :

- the plane is robust and hermetic;
- inefficiency of about 6% is compatible with the geometrical one due to spacers;
- uniformity of efficiency on the large scale (0.06 m2 area) is (94+/-2)%;
- > current in HV circuit is $1 \mu A$;
- noise at the plateau knee of about 0.45 Hz/cm2 is acceptable.



Conclusion

- Many efforts on gaseous DHCAL are going on in Europe.
- European DHCAL project has the ambition to be as close as possible to ILC detector requirements.
- European project is complementary to the american one.
- It is hoped that the two projects merge in the future.

Layout in 8 layers (solution1)



Layout in 6 layers (solution2)



Layer definition (except FPGA area)

| TOP LAYER | : Component layer+interconnect between hardroc and FPGA |
|---------------|---|
| GND | : Ground layer and access to internal layers |
| POWER | : Power to hardroc |
| ANALOG SIGNAL | : Layer to interconnect pad signals |
| BOTTOM | : RPC pads layer |

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Top layer and Pads (8 layers)



DAQ2 (needed for the m³)

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